

" Current status and issues of **SiC** wafers and **Si** wafers for power devices "

♪ Date and time: Tuesday, July 2, 2024, 13:00-17:10 ♪

Venue: Osaka Municipal University Nakamozu Campus Academic Exchange Hall

Multipurpose Hall <https://www.omu.ac.jp/about/campus/nakamozu/>

The current status of SiC wafers, which are being put to practical use as substrates for power devices, and Si wafers for power devices will be overviewed through presentations by major companies. Future issues will be discussed in light of the contents of the IEC (International Electrotechnical Commission) white paper on international standards for power semiconductors.

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12:30 Opening

13:00-13:05 Opening remarks

13:05-13:50 Overview of Resonac's **SiC** epiwafer business

Hiroshi Kanazawa (Resonac Inc. Device Solutions Division)

13:50-14:35 Current status of silicon wafers for power devices

Hiroyuki Tsubota (Global Wafers Japan, Technology Department)

14:35-14:50 Break

14:50-15:35 Development of **SiCkrest** bonded substrate

Motoki Kobayashi (Technical Department, Cycoc Corporation)

15:35-16:20 About Chinese **SiC substrate manufacturer TanKeBlue Semiconductor Co., Ltd.** Atsuro

Minami (Electronic Materials Department, New Metals and Chemicals Corporation)

16:20-17:05 Introduction of **the IEC White Paper "Power Semiconductors for an energy-wise society"**

Harufusa Kondo (Mitsubishi Electric Corporation, Power Device Works)

17:05-17:10 Closing remarks

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♪Registration: Please register and pay the registration fee online through the online registration system (click here*). Registration may close early due to limited seating. Please note that the materials on the day will be in PDF format. *If you would like to receive a printed copy of this information, please access the following link: <http://annex.jsap.or.jp/adps/pdf/kenkyuukai27.pdf>. ♪Registration Fee : (including tax)
Advanced Power Semiconductors

Subcommittee Members* 4,000 yen, Subcommittee Student Members Free, General 6,000 yen, General Students 1,000 yen *Those who are supporting members of the Advanced Power Semiconductors Subcommittee will be treated as members of the Advanced

Power Semiconductors Subcommittee. ♪Request for cooperation at the on-site event: If you have a fever, please refrain from attending on the day. Wearing a mask at the venue is optional.

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